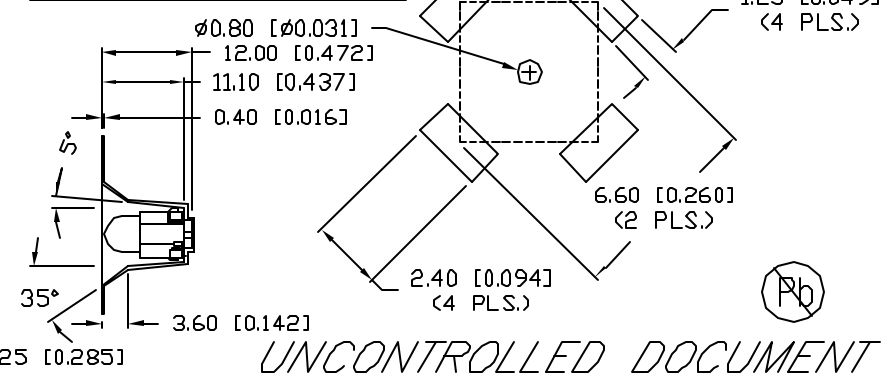


CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.
ESD CLASSIFICATION: CLASS II BASED ON MIL-STD 883E



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|-------------------------|----------------|-------------|-----|-------------------|----------------------|
| PEAK WAVELENGTH | | 635 (RED) | | nm | |
| | | 465 (BLUE) | | nm | |
| | | 520 (GREEN) | | nm | |
| FORWARD VOLTAGE | (R) | 2.2 | 2.7 | V_f | |
| | (B) | 3.4 | 4.0 | V_f | |
| | (G) | 3.4 | 4.0 | V_f | |
| REVERSE VOLTAGE | 5.0 | | | V_r | $I_r=100\mu\text{A}$ |
| AXIAL INTENSITY (R/B/G) | 1100/800/2200 | | | mcd | $I_f=20\text{mA}$ |
| VIEWING ANGLE | | 70 | | $2 \times \theta$ | |
| EMITTED COLOR | RED/BLUE/GREEN | | | | |
| EPOXY LENS FINISH | WATER CLEAR | | | | |

LIMITS OF SAFE OPERATION AT 25°C PER DIE.

| PARAMETER | COLORS | MAX | UNITS |
|-----------------------|--------|-------------|-------|
| PEAK FORWARD CURRENT* | R/B/G | 100 | mA |
| STEADY CURRENT | R/B/G | 30/20/20 | mA |
| POWER DISSIPATION | R/B/G | 95/80/80 | mW |
| DERATE FROM 25°C | | -1.2 | mW/°C |
| OPERATING TEMP. | | -30 TO +80 | °C |
| STORAGE TEMP. | | -40 TO +100 | °C |

* $T < 10\mu\text{s}$ RECOMMENDED PAD LAYOUT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005), LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=+DECIMAL PRECISION -0.00, MAX.=+0.00 -DECIMAL PRECISION

REV. PART NUMBER
SML-H1505SIUGUBCTR

5mm SURFACE MOUNT DOMED LED,
RED/BLUE/GREEN, WATER CLEAR LENS.

CONFIDENTIAL INFORMATION
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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



DRAWN BY: JUN
CHECKED BY:
APPROVED BY:
DATE: 03.31.08
PAGE: 1 OF 1
SCALE: N/A